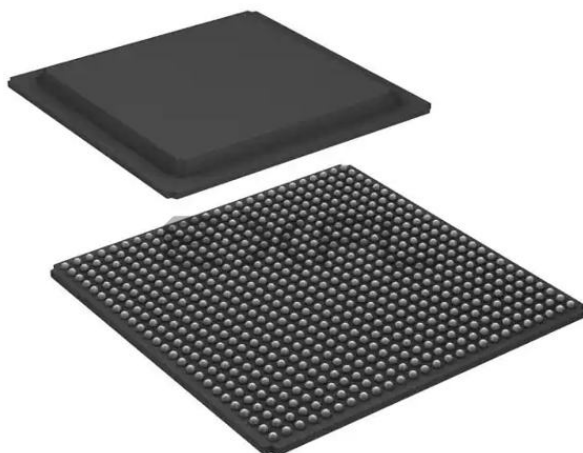




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2320
Number of Logic Elements/Cells	20880
Total RAM Bits	1622016
Number of I/O	404
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp20-6fg676c

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Virtex-II Pro Data Sheet

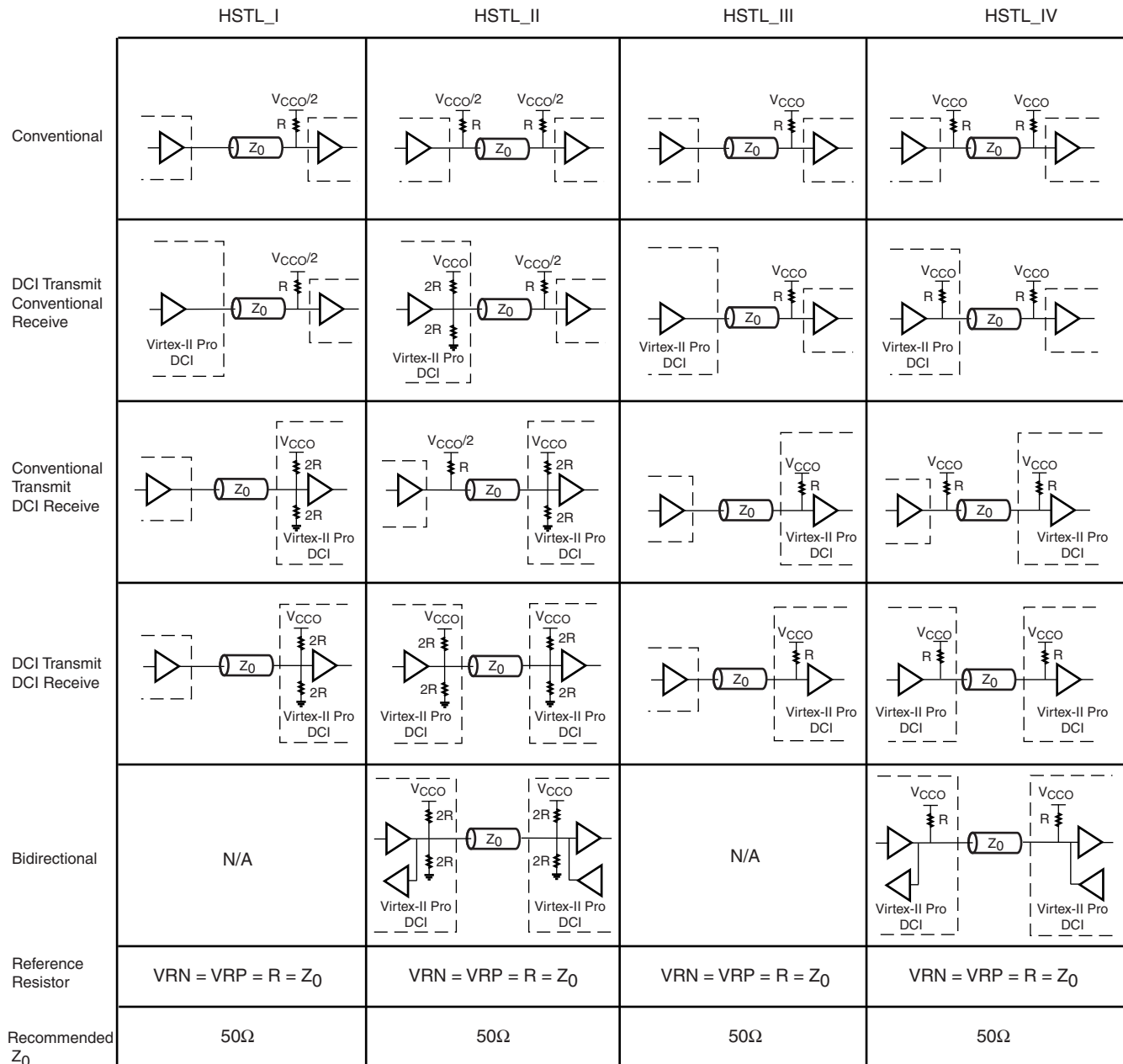
The Virtex-II Pro Data Sheet contains the following modules:

- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Introduction and Overview (Module 1)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description (Module 2)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics (Module 3)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Pinout Information (Module 4)

Table 15: SelectIO-Ultra Differential Buffers With On-Chip Termination

I/O Standard Description	IOSTANDARD Attribute	
	External Termination	On-Chip Termination
LVDS 2.5V	LVDS_25	LVDS_25_DCI
LVDS Extended 2.5V	LVDSEXT_25	LVDSEXT_25_DCI

Figure 28 provides examples illustrating the use of the HSTL_I_DCI, HSTL_II_DCI, HSTL_III_DCI, and HSTL_IV_DCI I/O standards. For a complete list, see the [Virtex-II Pro Platform FPGA User Guide](#).



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Figure 28: HSTL DCI Usage Examples

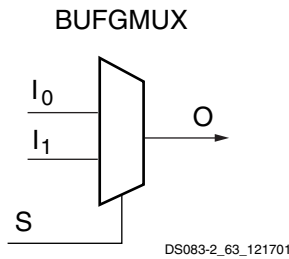


Figure 60: Virtex-II Pro BUFGMUX Function

If the presently selected clock is Low while S changes, or if it goes Low after S has changed, the output is kept Low until the other ("to-be-selected") clock has made a transition from High to Low. At that instant, the new clock starts driving the output.

The two clock inputs can be asynchronous with regard to each other, and the S input can change at any time, except for a short setup time prior to the rising edge of the presently selected clock (I0 or I1). Violating this setup time requirement can result in an undefined runt pulse output.

All Virtex-II Pro devices have 16 global clock multiplexer buffers.

Figure 61 shows a switchover from I0 to I1.

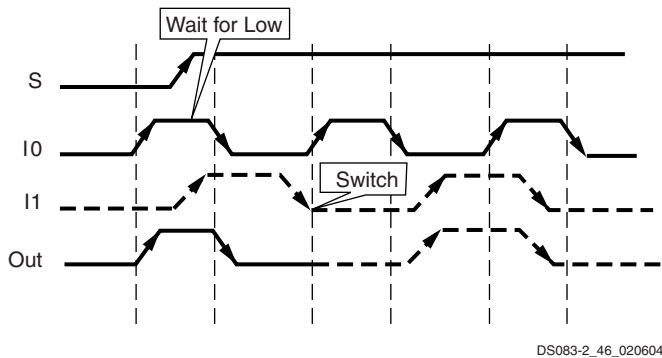


Figure 61: Clock Multiplexer Waveform Diagram

- The current clock is CLK0.
- S is activated High.
- If CLK0 is currently High, the multiplexer waits for CLK0 to go Low.
- Once CLK0 is Low, the multiplexer output stays Low until CLK1 transitions High to Low.
- When CLK1 transitions from High to Low, the output switches to CLK1.
- No glitches or short pulses can appear on the output.

Local Clocking

In addition to global clocks, there are local clock resources in the Virtex-II Pro devices. There are more than 72 local clocks in the Virtex-II Pro family. These resources can be used for many different applications, including but not limited to memory interfaces. For example, even using only the

left and right I/O banks, Virtex-II Pro FPGAs can support up to 50 local clocks for DDR SDRAM. These interfaces can operate beyond 200 MHz on Virtex-II Pro devices.

Digital Clock Manager (DCM)

The Virtex-II Pro DCM offers a wide range of powerful clock management features.

- **Clock De-skew:** The DCM generates new system clocks (either internally or externally to the FPGA), which are phase-aligned to the input clock, thus eliminating clock distribution delays.
- **Frequency Synthesis:** The DCM generates a wide range of output clock frequencies, performing very flexible clock multiplication and division.
- **Phase Shifting:** The DCM provides both coarse phase shifting and fine-grained phase shifting with dynamic phase shift control.

The DCM utilizes fully digital delay lines allowing robust high-precision control of clock phase and frequency. It also utilizes fully digital feedback systems, operating dynamically to compensate for temperature and voltage variations during operation.

Up to four of the nine DCM clock outputs can drive inputs to global clock buffers or global clock multiplexer buffers simultaneously (see Figure 62). All DCM clock outputs can simultaneously drive general routing resources, including routes to output buffers.

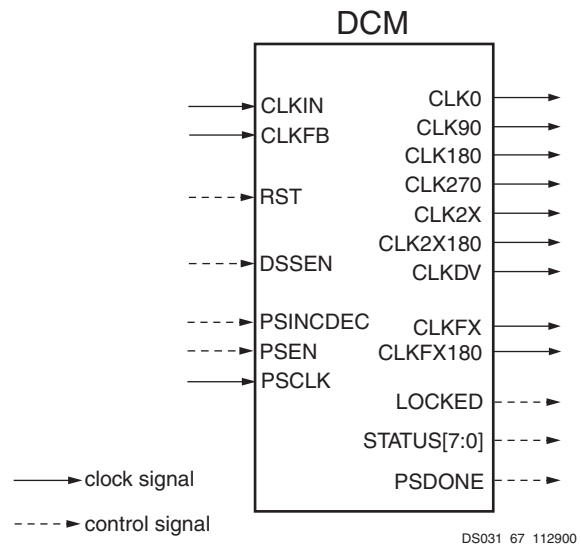


Figure 62: Digital Clock Manager

The DCM can be configured to delay the completion of the Virtex-II Pro configuration process until after the DCM has achieved lock. This guarantees that the chip does not begin operating until after the system clocks generated by the DCM have stabilized.



Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics

DS083 (v5.0) June 21, 2011

Product Specification

Virtex-II Pro⁽¹⁾ Electrical Characteristics

Virtex™-II Pro devices are provided in -7, -6, and -5 speed grades, with -7 having the highest performance.

Virtex-II Pro DC and AC characteristics are specified for both commercial and industrial grades. Except the operating temperature range or unless otherwise noted, all the DC and AC electrical parameters are the same for a particular speed grade (that is, the timing characteristics of a -6 speed grade industrial device are the same as for a -6 speed grade

commercial device). However, only selected speed grades and/or devices might be available in the industrial range.

All supply voltage and junction temperature specifications are representative of worst-case conditions. The parameters included are common to popular designs and typical applications. Contact Xilinx for design considerations requiring more detailed information.

All specifications are subject to change without notice.

Virtex-II Pro DC Characteristics

Table 1: Absolute Maximum Ratings

Symbol	Description ⁽¹⁾		Virtex-II Pro X	Virtex-II Pro	Units
V _{CCINT}	Internal supply voltage relative to GND		-0.5 to 1.6		V
V _{CCAUX}	Auxiliary supply voltage relative to GND		-0.5 to 3.0		V
V _{CCO}	Output drivers supply voltage relative to GND		-0.5 to 3.75		V
V _{BATT}	Key memory battery backup supply		-0.5 to 4.05		V
V _{REF}	Input reference voltage		-0.3 to 3.75		V
V _{IN}	3.3V I/O input voltage relative to GND (user and dedicated I/Os)		-0.3 to 4.05 ⁽³⁾		V
	2.5V or below I/O input voltage relative to GND (user and dedicated I/Os)		-0.5 to V _{CCO} + 0.5		V
V _{TS}	Voltage applied to 3-state 3.3V output (user and dedicated I/Os)		-0.3 to 4.05 ⁽³⁾		V
	Voltage applied to 3-state 2.5V or below output (user and dedicated I/Os)		-0.5 to V _{CCO} + 0.5		V
AVCCAUXRX	Receive auxiliary supply voltage relative to GNDA (analog ground)		-0.5 to 2.0	-0.5 to 3.0	V
AVCCAUTX	Transmit auxiliary supply voltage relative to GNDA (analog ground)		-0.5 to 3.0	-0.5 to 3.0	V
V _{TRX}	Terminal receive supply voltage relative to GND		-0.5 to 3.0	-0.5 to 3.0	V
V _{TTX}	Terminal transmit supply voltage relative to GND		-0.5 to 1.6	-0.5 to 3.0	V
T _{STG}	Storage temperature (ambient)		-65 to +150		°C
T _{SOL}	Maximum soldering temperature ⁽²⁾	All regular FG/FF flip-chip packages	+220		°C
		Pb-free FGG256 wire-bond package	N/A	+260	°C
		Pb-free FGG456 and FGG676 wire-bond packages	N/A	+250	°C
T _J	Maximum junction temperature ⁽²⁾		+125		°C

Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings might cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time might affect device reliability.
2. For soldering guidelines and thermal considerations, see the [Device Packaging and Thermal Characteristics Guide](#) information on the Xilinx website.
3. 3.3V I/O Absolute Maximum limit applied to DC and AC signals. Refer to [XAPP659](#) for more details.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device initialization. The actual current consumed depends on the power-on ramp rate of the power supply.

The V_{CCINT} power supply must ramp on, monotonically, no faster than 200 μ s and no slower than 50 ms. Ramp-on is defined as: 0 V_{DC} to minimum supply voltages (see [Table 2](#)).

V_{CCAUX} and V_{CCO} can power on at any ramp rate. Power supplies can be turned on in any sequence.

[Table 5](#) shows the minimum current required by Virtex-II Pro devices for proper power-on and configuration.

If the current minimums shown in [Table 5](#) are met, the device powers on properly after all three supplies have passed through their power-on reset threshold voltages.

Once initialized and configured, use the power calculator to estimate current drain on these supplies.

For more information on V_{CCAUX} , V_{CCO} , and configuration mode, refer to Chapter 3 in the *Virtex-II Pro Platform FPGA User Guide*.

Table 5: Power-On Current for Virtex-II Pro Devices

Symbol	Device											Units
	XC2VP2	XC2VP4	XC2VP7	XC2VP20	XC2VPX20	XC2VP30	XC2VP40	XC2VP50	XC2VP70	XC2VPX70	XC2VP100	
$I_{CCINTMIN}$	500	500	500	600	600	800	1050	1250	1700	1700	2200	mA
$I_{CCAUXMIN}$	250	250	250	250	250	250	250	250	250	250	250	mA
I_{CCOMIN}	100	100	100	100	100	100	100	100	100	100	100	mA

Notes:

1. Power-on current parameter values are specified for Commercial Grade. For Industrial Grade values, multiply Commercial Grade values by 1.5.
2. I_{CCOMIN} values listed here apply to the entire device (all banks).

General Power Supply Requirements

Proper decoupling of all FPGA power supplies is essential. Consult Xilinx Application Note [XAPP623](#) for detailed information on power distribution system design.

V_{CCAUX} powers critical resources in the FPGA. Therefore, this supply voltage is especially susceptible to power supply noise. V_{CCAUX} can share a power plane with V_{CCO} , but only if V_{CCO} does not have excessive noise. Staying within simultaneously switching output (SSO) limits is essential for keeping power supply noise to a minimum. Refer to

[XAPP689](#), "Managing Ground Bounce in Large FPGAs," to determine the number of simultaneously switching outputs allowed per bank at the package level.

Changes in V_{CCAUX} voltage beyond 200 mV peak-to-peak should take place at a rate no faster than 10 mV per millisecond.

Recommended practices that can help reduce jitter and period distortion are described in Xilinx Answer Record 13756.

RocketIO Switching Characteristics

Table 22: RocketIO X Reference Clock Switching Characteristics

Description	Symbol	Conditions	All Speed Grades			Units
			Min	Typ	Max	
Reference Clock frequency range ⁽¹⁾	F _{GCLK}		62.5		425	MHz
Reference Clock frequency tolerance	F _{GTOL}				±350	ppm
Reference Clock rise time	T _{RCLK}	20% – 80%		75		ps
Reference Clock fall time	T _{FCLK}	20% – 80%		75		ps
Reference Clock duty cycle	T _{DCREF}		45	50	55	%
Reference Clock total jitter, peak-peak	T _{GJTT}	3.125 Gb/s – 6.25 Gb/s			30	ps
		2.488 Gb/s – 3.125 Gb/s			40	ps
Clock recovery frequency acquisition time, from Power-up to High state of PMARXLOCK	T _{LOCK}			100		μs
Clock recovery phase acquisition time, from Data to High state of PMARXLOCK	T _{PHASE}			40	60	μs

Notes:

1. BREFCLK should be used for all serial bit rates up to the maximum shown.

Table 23: RocketIO Reference Clock Switching Characteristics

Description	Symbol	Conditions	All Speed Grades			Units
			Min	Typ	Max	
Reference Clock frequency range ⁽¹⁾	F _{GCLK}	Full rate operation	50		156.25	MHz
		Half rate operation ⁽²⁾ (2X oversampling)	60		100	MHz
Reference Clock frequency tolerance	F _{GTOL}				±100	ppm
Reference Clock rise time	T _{RCLK}	20% – 80%		600	1000	ps
Reference Clock fall time	T _{FCLK}	20% – 80%		600	1000	ps
Reference Clock duty cycle	T _{DCREF}		45	50	55	%
Reference Clock total jitter, peak-peak ⁽³⁾	T _{GJTT}	2.501 Gb/s – 3.125 Gb/s			40	ps
		1.061 Gb/s – 2.5 Gb/s			50	ps
		< 1.06 Gb/s			120	ps
Clock recovery frequency acquisition time	T _{LOCK}				10	μs
Clock recovery phase acquisition time	T _{PHASE}			960		bits ⁽⁴⁾

Notes:

1. BREFCLK/BREFCLK2 can be used for all serial bit rates up to the maximum shown. REFCLK/REFCLK2 can be used for serial bit rates up to 2.5 Gb/s (REFCLK = 125 MHz). All other parameters apply equally to REFCLK, REFCLK2, BREFCLK, and BREFCLK2 except as noted.
2. For serial rates under 1 Gb/s, the 3X (or greater) oversampling techniques described in [XAPP572](#) are required to meet the transmit jitter and receive jitter tolerance specifications defined in this data sheet.
3. Measured at the package pin. For reference clock frequencies equal to or above 125 MHz, BREFCLK/BREFCLK2 must be used.
4. 8B/10B-type bitstream.

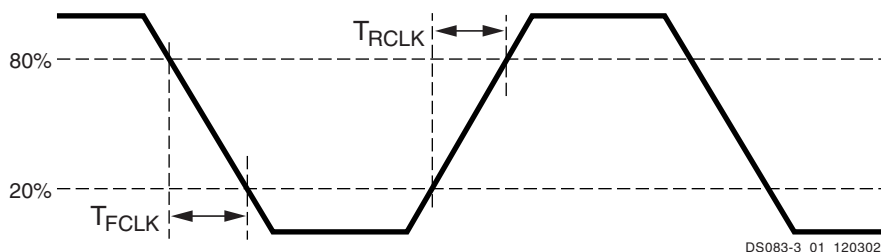


Figure 3: Reference Clock Timing Parameters

Table 6: FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
7	IO_L88N_7/VREF_7	L5			
7	IO_L86P_7	L6			
7	IO_L86N_7	K6			
7	IO_L85P_7	K1			
7	IO_L85N_7	K2			
7	IO_L60P_7	K3	NC		
7	IO_L60N_7	K4	NC		
7	IO_L58P_7	K5	NC		
7	IO_L58N_7/VREF_7	J5	NC		
7	IO_L56P_7	J1	NC		
7	IO_L56N_7	J2	NC		
7	IO_L55P_7	J3	NC		
7	IO_L55N_7	J4	NC		
7	IO_L54P_7	J6	NC		
7	IO_L54N_7	H5	NC		
7	IO_L52P_7	H1	NC		
7	IO_L52N_7/VREF_7	H2	NC		
7	IO_L50P_7	H3	NC		
7	IO_L50N_7	H4	NC		
7	IO_L49P_7	G1	NC		
7	IO_L49N_7	G2	NC		
7	IO_L48P_7	G3	NC		
7	IO_L48N_7	G4	NC		
7	IO_L46P_7	G5	NC		
7	IO_L46N_7/VREF_7	F5	NC		
7	IO_L43P_7	F1	NC		
7	IO_L43N_7	F2	NC		
7	IO_L06P_7	F3			
7	IO_L06N_7	F4			
7	IO_L04P_7	E1			
7	IO_L04N_7/VREF_7	E2			
7	IO_L03P_7	E3			
7	IO_L03N_7	E4			
7	IO_L02P_7	D1			
7	IO_L02N_7	D2			
7	IO_L01P_7/VRN_7	C1			
7	IO_L01N_7/VRP_7	C2			

Table 8: FF672 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
7	VCCO_7	L18			
7	VCCO_7	M18			
7	VCCO_7	N18			
N/A	CCLK	W7			
N/A	PROG_B	D22			
N/A	DONE	AB6			
N/A	M0	AC22			
N/A	M1	W20			
N/A	M2	AB21			
N/A	TCK	G8			
N/A	TDI	H20			
N/A	TDO	H7			
N/A	TMS	F7			
N/A	PWRDWN_B	AC5			
N/A	HSWAP_EN	E21			
N/A	RSVD	D5			
N/A	VBATT	E6			
N/A	DXP	F20			
N/A	DXN	G19			
N/A	AVCCAUXTX7	B11			
N/A	VTTXPAD7	B12			
N/A	TXNPAD7	A12			
N/A	TXPPAD7	A11			
N/A	GND7	C11			
N/A	RXPPAD7	A10			
N/A	RXNPAD7	A9			
N/A	VTRXPAD7	B10			
N/A	AVCCAUXRX7	B9			
N/A	AVCCAUXTX9	B6	NC	NC	
N/A	VTTXPAD9	B7	NC	NC	
N/A	TXNPAD9	A7	NC	NC	
N/A	TXPPAD9	A6	NC	NC	
N/A	GND9	C5	NC	NC	
N/A	RXPPAD9	A5	NC	NC	
N/A	RXNPAD9	A4	NC	NC	
N/A	VTRXPAD9	B5	NC	NC	

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
6	IO_L02P_6		AH26			
6	IO_L02N_6		AG26			
6	IO_L03P_6		AH29			
6	IO_L03N_6/VREF_6		AH30			
6	IO_L04P_6		AH27			
6	IO_L04N_6		AG28			
6	IO_L05P_6		AD25			
6	IO_L05N_6		AD26			
6	IO_L06P_6		AG29			
6	IO_L06N_6		AG30			
6	IO_L31P_6		AF25	NC		
6	IO_L31N_6		AE26	NC		
6	IO_L32P_6		AB23	NC		
6	IO_L32N_6		AB24	NC		
6	IO_L33P_6		AE27	NC		
6	IO_L33N_6/VREF_6		AE28	NC		
6	IO_L34P_6		AF27	NC		
6	IO_L34N_6		AF28	NC		
6	IO_L35P_6		AC25	NC		
6	IO_L35N_6		AC26	NC		
6	IO_L36P_6		AF29	NC		
6	IO_L36N_6		AF30	NC		
6	IO_L37P_6		AD27	NC		
6	IO_L37N_6		AD28	NC		
6	IO_L38P_6		AA23	NC		
6	IO_L38N_6		AA24	NC		
6	IO_L39P_6		AE29	NC		
6	IO_L39N_6/VREF_6		AE30	NC		
6	IO_L40P_6		AB25	NC		
6	IO_L40N_6		AB26	NC		
6	IO_L41P_6		Y23	NC		
6	IO_L41N_6		Y24	NC		
6	IO_L42P_6		AD29	NC		
6	IO_L42N_6		AD30	NC		
6	IO_L43P_6		AC27			
6	IO_L43N_6		AC28			

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	RXPPAD7		A12			
N/A	RXNPAD7		A11			
N/A	VTRXPAD7		B12			
N/A	AVCCAUXRX7		B11			
N/A	AVCCAUXTX9		B6			
N/A	VTTXPAD9		B7			
N/A	TXNPAD9		A7			
N/A	TXPPAD9		A6			
N/A	GND A9		C6			
N/A	RXPPAD9		A5			
N/A	RXNPAD9		A4			
N/A	VTRXPAD9		B5			
N/A	AVCCAUXRX9		B4			
N/A	AVCCAUXRX16		AJ4			
N/A	VTRXPAD16		AJ5			
N/A	RXNPAD16		AK4			
N/A	RXPPAD16		AK5			
N/A	GND A16		AH6			
N/A	TXPPAD16		AK6			
N/A	TXNPAD16		AK7			
N/A	VTTXPAD16		AJ7			
N/A	AVCCAUXTX16		AJ6			
N/A	AVCCAUXRX18		AJ11			
N/A	VTRXPAD18		AJ12			
N/A	RXNPAD18		AK11			
N/A	RXPPAD18		AK12			
N/A	GND A18		AH12			
N/A	TXPPAD18		AK13			
N/A	TXNPAD18		AK14			
N/A	VTTXPAD18		AJ14			
N/A	AVCCAUXTX18		AJ13			
N/A	AVCCAUXRX19		AJ17			
N/A	VTRXPAD19		AJ18			
N/A	RXNPAD19		AK17			
N/A	RXPPAD19		AK18			
N/A	GND A19		AH19			

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
1	IO_L37N_1	G13				
1	IO_L37P_1	H13				
1	IO_L27N_1/VREF_1	J13	NC	NC		
1	IO_L27P_1	K13	NC	NC		
1	IO_L26N_1	D8	NC	NC		
1	IO_L26P_1	E8	NC	NC		
1	IO_L25N_1	F12	NC	NC		
1	IO_L25P_1	G12	NC	NC		
1	IO_L21N_1	G11	NC	NC		
1	IO_L21P_1	H11	NC	NC		
1	IO_L20N_1	C7	NC	NC		
1	IO_L20P_1	D7	NC	NC		
1	IO_L19N_1	E11	NC	NC		
1	IO_L19P_1	F11	NC	NC		
1	IO_L09N_1/VREF_1	J12				
1	IO_L09P_1	K12				
1	IO_L08N_1	D6				
1	IO_L08P_1	D5				
1	IO_L07N_1	E9				
1	IO_L07P_1	F9				
1	IO_L06N_1	J11				
1	IO_L06P_1	K11				
1	IO_L05_1/No_Pair	J10				
1	IO_L03N_1/VREF_1	G10				
1	IO_L03P_1	H10				
1	IO_L02N_1	G9				
1	IO_L02P_1	H9				
1	IO_L01N_1/VRP_1	E7				
1	IO_L01P_1/VRN_1	E6				
2	IO_L01N_2/VRP_2	D2				
2	IO_L01P_2/VRN_2	D1				
2	IO_L02N_2	F8				
2	IO_L02P_2	F7				
2	IO_L03N_2	E4				
2	IO_L03P_2	E3				
2	IO_L04N_2/VREF_2	E2				
2	IO_L04P_2	E1				

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
1	VCCO_1	L15				
1	VCCO_1	M13				
1	VCCO_1	M14				
1	VCCO_1	M15				
1	VCCO_1	M16				
1	VCCO_1	M17				
2	VCCO_2	F3				
2	VCCO_2	K6				
2	VCCO_2	M11				
2	VCCO_2	N11				
2	VCCO_2	N12				
2	VCCO_2	P11				
2	VCCO_2	P12				
2	VCCO_2	R5				
2	VCCO_2	R11				
2	VCCO_2	R12				
2	VCCO_2	T12				
2	VCCO_2	U12				
3	VCCO_3	V12				
3	VCCO_3	W12				
3	VCCO_3	Y5				
3	VCCO_3	Y11				
3	VCCO_3	Y12				
3	VCCO_3	AA11				
3	VCCO_3	AA12				
3	VCCO_3	AB11				
3	VCCO_3	AB12				
3	VCCO_3	AC11				
3	VCCO_3	AE6				
3	VCCO_3	AJ3				
4	VCCO_4	AC13				
4	VCCO_4	AC14				
4	VCCO_4	AC15				
4	VCCO_4	AC16				
4	VCCO_4	AC17				
4	VCCO_4	AD12				
4	VCCO_4	AD13				
4	VCCO_4	AD14				

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
1	IO_L36N_1/VREF_1	E13	NC	
1	IO_L36P_1	D13	NC	
1	IO_L35N_1	K15	NC	
1	IO_L35P_1	J15	NC	
1	IO_L34N_1	G13	NC	
1	IO_L34P_1	F12	NC	
1	IO_L30N_1	J13	NC	
1	IO_L30P_1	H13	NC	
1	IO_L29N_1	L15	NC	
1	IO_L29P_1	L14	NC	
1	IO_L28N_1	E12	NC	
1	IO_L28P_1	D12	NC	
1	IO_L27N_1/VREF_1	J12		
1	IO_L27P_1	H12		
1	IO_L26N_1	K14		
1	IO_L26P_1	J14		
1	IO_L25N_1	D11		
1	IO_L25P_1	C11		
1	IO_L21N_1	F11		
1	IO_L21P_1	E11		
1	IO_L20N_1	M14		
1	IO_L20P_1	M13		
1	IO_L19N_1	H11		
1	IO_L19P_1	G11		
1	IO_L09N_1/VREF_1	J11		
1	IO_L09P_1	J10		
1	IO_L08N_1	L13		
1	IO_L08P_1	L12		
1	IO_L07N_1	D10		
1	IO_L07P_1	C10		
1	IO_L06N_1	F10		
1	IO_L06P_1	E10		
1	IO_L05_1/No_Pair	K10		
1	IO_L03N_1/VREF_1	H10		
1	IO_L03P_1	G10		
1	IO_L02N_1	K12		
1	IO_L02P_1	K11		
1	IO_L01N_1/VRP_1	E9		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
4	IO_L66P_4/VREF_4	AU19		
4	IO_L67N_4	AM19		
4	IO_L67P_4	AL19		
4	IO_L68N_4	AK19		
4	IO_L68P_4	AJ19		
4	IO_L69N_4	AP19		
4	IO_L69P_4/VREF_4	AN19		
4	IO_L73N_4	AT19		
4	IO_L73P_4	AR19		
4	IO_L74N_4/GCLK3S	AH20		
4	IO_L74P_4/GCLK2P	AG20		
4	IO_L75N_4/GCLK1S	AL20		
4	IO_L75P_4/GCLK0P	AK20		
5	IO_L75N_5/GCLK7S	AR20		
5	IO_L75P_5/GCLK6P	AT20		
5	IO_L74N_5/GCLK5S	AH21		
5	IO_L74P_5/GCLK4P	AJ21		
5	IO_L73N_5	AP20		
5	IO_L73P_5	AP21		
5	IO_L69N_5/VREF_5	AU21		
5	IO_L69P_5	AU22		
5	IO_L68N_5	AK21		
5	IO_L68P_5	AL21		
5	IO_L67N_5	AR21		
5	IO_L67P_5	AT21		
5	IO_L66N_5/VREF_5	AN21		
5	IO_L66P_5	AN22		
5	IO_L65N_5	AM20		
5	IO_L65P_5	AM21		
5	IO_L64N_5	AR22		
5	IO_L64P_5	AT22		
5	IO_L60N_5	AP22		
5	IO_L60P_5	AR23		
5	IO_L59N_5	AG21		
5	IO_L59P_5	AG22		
5	IO_L58N_5	AL22		
5	IO_L58P_5	AM22		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
7	IO_L86N_7	W28		
7	IO_L85P_7	W34		
7	IO_L85N_7	W35		
7	IO_L60P_7	W32		
7	IO_L60N_7	W33		
7	IO_L59P_7	W29		
7	IO_L59N_7	W30		
7	IO_L58P_7	V38		
7	IO_L58N_7/VREF_7	V39		
7	IO_L57P_7	V36		
7	IO_L57N_7	V37		
7	IO_L56P_7	V28		
7	IO_L56N_7	V29		
7	IO_L55P_7	V34		
7	IO_L55N_7	V35		
7	IO_L54P_7	V32		
7	IO_L54N_7	V33		
7	IO_L53P_7	V30		
7	IO_L53N_7	V31		
7	IO_L52P_7	U38		
7	IO_L52N_7/VREF_7	U39		
7	IO_L51P_7	T36		
7	IO_L51N_7	U36		
7	IO_L50P_7	V27		
7	IO_L50N_7	U27		
7	IO_L49P_7	U34		
7	IO_L49N_7	U35		
7	IO_L48P_7	T37		
7	IO_L48N_7	T38		
7	IO_L47P_7	U30		
7	IO_L47N_7	U31		
7	IO_L46P_7	T33		
7	IO_L46N_7/VREF_7	T34		
7	IO_L45P_7	R38		
7	IO_L45N_7	R39		
7	IO_L44P_7	T32		
7	IO_L44N_7	U32		
7	IO_L43P_7	R36		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	GND	AU3		
N/A	GND	AT3		
N/A	GND	D3		
N/A	GND	C3		
N/A	GND	B3		
N/A	GND	AN12		
N/A	GND	G12		
N/A	GND	C12		
N/A	GND	Y10		
N/A	GND	AH9		
N/A	GND	AD9		
N/A	GND	T9		
N/A	GND	M9		
N/A	GND	AU8		
N/A	GND	AN8		
N/A	GND	G8		
N/A	GND	C8		
N/A	GND	Y6		
N/A	GND	AM5		
N/A	GND	AH5		
N/A	GND	T17		
N/A	GND	AT16		
N/A	GND	AN16		
N/A	GND	AJ16		
N/A	GND	AC16		
N/A	GND	AB16		
N/A	GND	AA16		
N/A	GND	Y16		
N/A	GND	W16		
N/A	GND	V16		
N/A	GND	U16		
N/A	GND	L16		
N/A	GND	G16		
N/A	GND	D16		
N/A	GND	AU12		
N/A	GND	AB18		
N/A	GND	AA18		
N/A	GND	Y18		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
4	IO_L09N_4		AR11		
4	IO_L09P_4/VREF_4		AP11		
4	IO_L19N_4		AV11		
4	IO_L19P_4		AU11		
4	IO_L20N_4		AY10		
4	IO_L20P_4		AY11		
4	IO_L21N_4		AN12		
4	IO_L21P_4		AM12		
4	IO_L25N_4		AR12		
4	IO_L25P_4		AP12		
4	IO_L26N_4		AT12		
4	IO_L26P_4		AU12		
4	IO_L27N_4		AW12		
4	IO_L27P_4/VREF_4		AV12		
4	IO_L28N_4		AM13		
4	IO_L28P_4		AL13		
4	IO_L29N_4		AP13		
4	IO_L29P_4		AN13		
4	IO_L30N_4		AT13		
4	IO_L30P_4		AR13		
4	IO_L34N_4		AV13		
4	IO_L34P_4		AU13		
4	IO_L35N_4		AW13		
4	IO_L35P_4		AY13		
4	IO_L36N_4		AL15		
4	IO_L36P_4/VREF_4		AL14		
4	IO_L78N_4		AN14	NC	
4	IO_L78P_4		AM14	NC	
4	IO_L83_4/No_Pair		AR14	NC	
4	IO_L84N_4		AU14	NC	
4	IO_L84P_4		AT14	NC	
4	IO_L85N_4		AW14	NC	
4	IO_L85P_4		AV14	NC	
4	IO_L86N_4		AM15	NC	
4	IO_L86P_4		AN15	NC	
4	IO_L87N_4		AR15	NC	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
1	IO_L57P_1	E19	
1	IO_L56N_1	K18	
1	IO_L56P_1	J18	
1	IO_L55N_1	H19	
1	IO_L55P_1	H20	
1	IO_L54N_1	B18	
1	IO_L54P_1	A18	
1	IO_L53_1/No_Pair	L18	
1	IO_L50_1/No_Pair	L19	
1	IO_L49N_1	C18	
1	IO_L49P_1	C19	
1	IO_L48N_1	F18	
1	IO_L48P_1	E18	
1	IO_L47N_1	L17	
1	IO_L47P_1	K17	
1	IO_L46N_1	G18	
1	IO_L46P_1	G19	
1	IO_L18N_1/VREF_1	C17	NC
1	IO_L18P_1	B17	NC
1	IO_L12N_1	G17	NC
1	IO_L12P_1	F17	NC
1	IO_L11N_1	M17	NC
1	IO_L11P_1	M18	NC
1	IO_L10N_1	B16	NC
1	IO_L10P_1	A16	NC
1	IO_L45N_1/VREF_1	D16	
1	IO_L45P_1	D17	
1	IO_L44N_1	K16	
1	IO_L44P_1	J16	
1	IO_L43N_1	F16	
1	IO_L43P_1	E16	
1	IO_L39N_1	H16	
1	IO_L39P_1	H17	
1	IO_L38N_1	M16	
1	IO_L38P_1	L16	
1	IO_L37N_1	B15	
1	IO_L37P_1	A15	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
4	IO_L58P_4	AW19	
4	IO_L59N_4	AP19	
4	IO_L59P_4	AN19	
4	IO_L60N_4	BB19	
4	IO_L60P_4	BA19	
4	IO_L64N_4	AU20	
4	IO_L64P_4	AT20	
4	IO_L65N_4	AL21	
4	IO_L65P_4	AL20	
4	IO_L66N_4	BA20	
4	IO_L66P_4/VREF_4	AY20	
4	IO_L67N_4	AR21	
4	IO_L67P_4	AP21	
4	IO_L68N_4	AN20	
4	IO_L68P_4	AM20	
4	IO_L69N_4	AU21	
4	IO_L69P_4/VREF_4	AT21	
4	IO_L73N_4	AW21	
4	IO_L73P_4	AV21	
4	IO_L74N_4/GCLK3S	AN21	
4	IO_L74P_4/GCLK2P	AM21	
4	IO_L75N_4/GCLK1S	BA21	
4	IO_L75P_4/GCLK0P	AY21	
5	IO_L75N_5/GCLK7S	AY22	
5	IO_L75P_5/GCLK6P	BA22	
5	IO_L74N_5/GCLK5S	AM22	
5	IO_L74P_5/GCLK4P	AN22	
5	IO_L73N_5	AV22	
5	IO_L73P_5	AW22	
5	IO_L69N_5/VREF_5	AT22	
5	IO_L69P_5	AU22	
5	IO_L68N_5	AM23	
5	IO_L68P_5	AN23	
5	IO_L67N_5	AP22	
5	IO_L67P_5	AR22	
5	IO_L66N_5/VREF_5	AY23	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	GND	AC25	
N/A	GND	AB25	
N/A	GND	AA25	
N/A	GND	Y25	
N/A	GND	W25	
N/A	GND	V25	
N/A	GND	U25	
N/A	GND	AL24	
N/A	GND	AF24	
N/A	GND	AE24	
N/A	GND	AD24	
N/A	GND	AC24	
N/A	GND	AB24	
N/A	GND	AA24	
N/A	GND	Y24	
N/A	GND	W24	
N/A	GND	V24	
N/A	GND	U24	
N/A	GND	M24	
N/A	GND	BB23	
N/A	GND	AV23	
N/A	GND	AP23	
N/A	GND	AF23	
N/A	GND	AE23	
N/A	GND	AD23	
N/A	GND	AC23	
N/A	GND	AB23	
N/A	GND	AA23	
N/A	GND	Y23	
N/A	GND	W23	
N/A	GND	V23	
N/A	GND	U23	
N/A	GND	J23	
N/A	GND	E23	
N/A	GND	A23	
N/A	GND	AF22	
N/A	GND	AE22	